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This listing of claims will replace all prior versions of claims in the application.

Claim 1. (currently amended) A method for preparation of a photoresist composition comprising:

(a) treating a prepared resin with one or more organic solvents chosen from among a halogenated solvent and an alkane solvent, the resin comprising phenolic and alkyl acrylate photoacid labile groups;

(b) admixing the treated resin with a photoactive component to provide a photoresist composition.

Claim 2. (original) The method of claim 1 wherein the resin has been isolated from a resin synthesis mixture prior to treatment with one or more organic solvents.

Claim 3. (original) The method of claim 1 wherein the treatment with one or more organic solvents separates low molecular weight species of the resin from higher molecular weight species of the polymer.

Claim 4. (original) The method of claim 1 wherein treatment with the one or more organic solvents removes resin species having a Mw of about 2,000 or less.

Claim 5. (currently amended) The method of claim 1 wherein treatment with the one or more organic solvents removes resin species having a Mw of about ~~1,000~~ 100 or less.

Claim 6. (original) The method of claim 1 wherein treatment with the one or more organic solvents removes resin species having a Mw of about 500 or less.

Claim 7. (original) The method of claim 1 wherein the resin is treated with methylene chloride.

Claim 8. (original) The method of claim 1 wherein the resin is treated with one or more of a halogenated solvent; a solvent having an ester; a lactate; a hydroxy-containing solvent; an ether; or an alkane.

Claim 9. (original) The method of claim 1 wherein the resin is treated with one or more of chloroform, ethyl acetate, anisole, ethyl lactate, methyl lactate, a glycol, methanol, ethanol, hexane, or heptane.

Claim 10. (original) The method of claim 1 wherein the resin is washed with the one or more organic solvents.

Claim 11. (original) The method of claim 1 wherein the resin is extracted with the one or more organic solvents.

Claim 12. (original) The method of claim 1 wherein the resin is soxhlet extracted with the one or more organic solvents.

Claims 13-14. (cancelled)

Claim 15. (original) The method of claim 1 wherein the resin binder is a phenolic polymer with pendant inert blocking groups.

Claims 16-24. (cancelled)

Claim 25. (previously presented) The method of claim 1 wherein the resin is treated with a halogenated solvent.

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Claim 26. (previously presented) The method of claim 1 wherein the resin is treated with a solvent having an ester.

Claim 27. (previously presented) The method of claim 1 wherein the resin is treated with a lactate.

Claim 28. (previously presented) The method of claim 1 wherein the resin is treated with a hydroxy-containing solvent.

Claim 29. (previously presented) The method of claim 1 wherein the resin is treated with an alkane solvent.

Claim 30. (previously presented) A method for preparation of a photoresist composition comprising:

- (a) washing a prepared resin with one or more organic solvents, the resin comprising phenolic and alkyl acrylate photoacid labile groups;
- (b) admixing the treated resin with a photoactive component to provide a photoresist composition.

Claim 31. (currently amended) The method of claim ~~30~~ 29 wherein the resin is washed with methylene chloride.

Claim 32. (currently amended) The method of claim ~~30~~ 29 wherein the resin is washed with a halogenated solvent.

Claim 33. (currently amended) The method of claim ~~30~~ 29 wherein the resin is washed with a solvent having an ester.

Claim 34. (currently amended) The method of claim ~~30~~ 29 wherein the resin is washed with a lactate.

Claim 35. (currently amended) The method of claim ~~30~~ 29 wherein the resin is treated with a hydroxy-containing solvent.

Claim 36. (currently amended) The method of claim ~~30~~ 29 wherein the resin is treated with an alkane solvent.

Claims 37-45. (cancelled)